CLAIMS

[Claim 1]

A substrate processing apparatus for processing a substrate, the substrate processing apparatus comprising:

composite modules in each of which one transfer chamber having a transfer space for the substrate and a processing chamber having a processing space for the substrate are integrated, wherein

the composite modules are connected by connecting the transfer chambers adjacent to each other.

[Claim 2]

The substrate processing apparatus according to claim 1, wherein

the transfer chambers adjacent to each other are connected to each other directly.

[Claim 3]

The substrate processing apparatus according to claim 1, wherein

the transfer spaces of the transfer chambers connected to each other communicate with each other.

[Claim 4]

The substrate processing apparatus according to claim 3, wherein

a magnetic levitation transfer unit is provided in the transfer space.

[Claim 5]

The substrate processing apparatus according to claim 3, wherein

at least one of the transfer chambers is provided with a transfer unit fixed to the transfer chamber.

[Claim 6]

The substrate processing apparatus according to claim 3, wherein

the transfer space is maintained in a vacuum atmosphere,

the substrate processing apparatus further comprises:

a load-lock module switchable between an atmospheric atmosphere and the vacuum atmosphere, and

a connection module that connects the transfer chamber and the load-lock

module, and

an exhaust port configured to vacuum the transfer space is formed in the connection module.

[Claim 7]

The substrate processing apparatus according to claim 3, wherein

the transfer space is maintained in a vacuum atmosphere, and

an exhaust port configured to vacuum the transfer space is formed in one of the transfer chambers.

[Claim 8]

The substrate processing apparatus according to claim 1, wherein

openings having a same shape are formed at both end surfaces of the transfer chamber.

[Claim 9]

The substrate processing apparatus according to claim 1, wherein

each of the composite modules has a configuration in which one chamber is partitioned into the one transfer chamber and the processing chamber.

[Claim 10]

The substrate processing apparatus according to claim 1, wherein

each of the composite modules has two or more of the processing chambers.

[Claim 11]

The substrate processing apparatus according to claim 10, wherein

each of the composite modules has three or more of the processing chambers.

[Claim 12]

The substrate processing apparatus according to claim 1, wherein

each of the composite modules has a pit-in chamber in which a maintenance unit is accommodated.

[Claim 13]

The substrate processing apparatus according to claim 1, wherein

an apparatus required for processing the substrate is commonly provided in two or more of the processing chambers.

[Claim 14]

The substrate processing apparatus according to claim 13, wherein

the apparatus is disposed in at least one of an upper common area formed above the transfer chamber and a lower common area formed below the transfer chambers in each of the composite modules.